

MOLD AND METHOD FOR MANUFACTURING MOLD

ABSTRACT

Provided is a technology for suppressing, in a mold having a heat-insulating layer formed therein, a problem of chipping of the heat-insulating layer and the like even when a penetrating member is inserted through a through-hole provided in the mold. The mold is provided with a mold body having a convex part on an inner wall surface of the mold body, a heat-insulating layer arranged on the inner wall surface, and a through-hole which penetrates the convex part in a thickness direction of the mold body and through which the penetrating member can be inserted. An outer periphery of the through-hole is inside an outer periphery of a top surface of the convex part. A spacing between the outer periphery of the through-hole on the top surface of the convex part and the outer periphery of the top surface of the convex part is preferably 0.5 mm or less.

FIG. 1